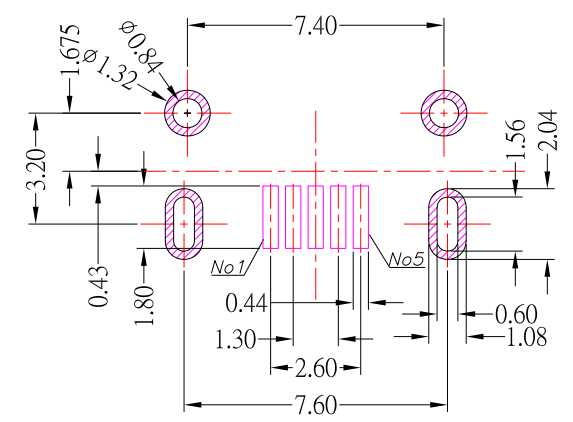
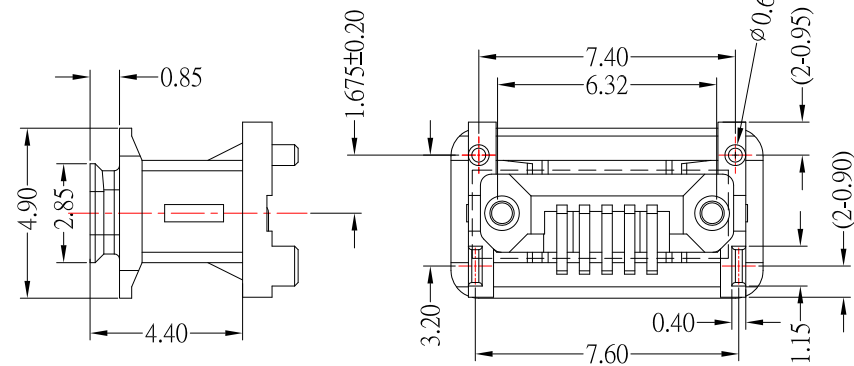
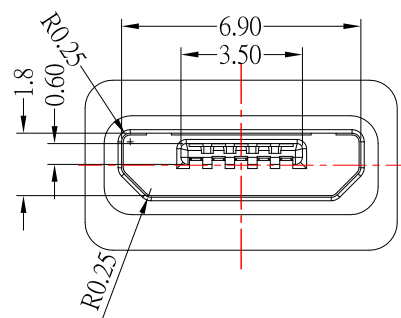
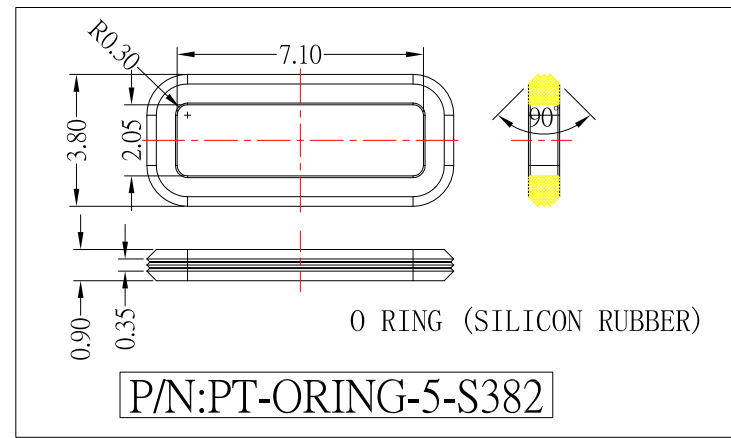
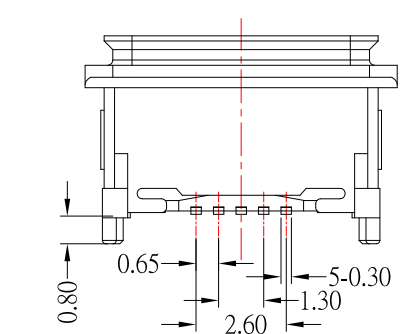


MRUSB-5B-WP9VB-x-S382

鍍層厚度：
Blank : 1u"
2 : 15u"
3 : 30u"



P.C.B LAYOUT MOUNTING PATTERN



- NOTES:
- MATERIAL:
- 1.1 HOUSING: LCP
 - 1.2 CONTACT: BRASS
 - 1.3 SHELL: SUS
- FINISH:
- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
 - 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.SPECIFICATION:
- 3.1 RATING: 1.8 A(PIN1,5) ; 1.0A (PIN2,3,4) , 30VAC
 - 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 VAC
 - 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
 - 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

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DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S

UNITS MM

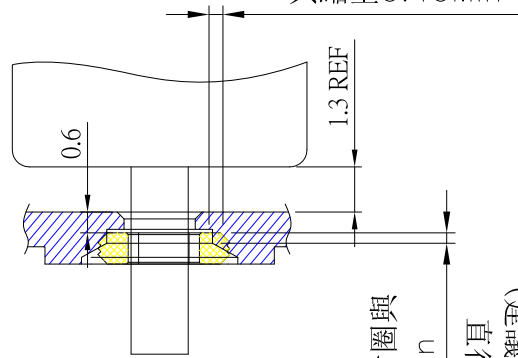
DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	06/30/21	FINISH	MODLE	MICRO 5B/F 立式SMT IPX7 外殼腳: 1.15X0.4X0.75mm 支架寬 5.0 mm
CHECKED BY:	DATE	SCALE	DWG NO.	MRUSB-5B-WP9VB-x-S382
Jacky Chen	06/30/21	1 : 1	PART NO.	MRUSB-5B-WP9VB-x-S382
APPROVED BY:	DATE	SHEET NO.	1 of 2	SIZE A4 VER R2
Tony Kao	06/30/21			

2	更新圖面	Jack	063021
1	更新MODLE	Jack	061721
ITEM NO.	DESCRIPTION	DRAWN	DATE

IPX7

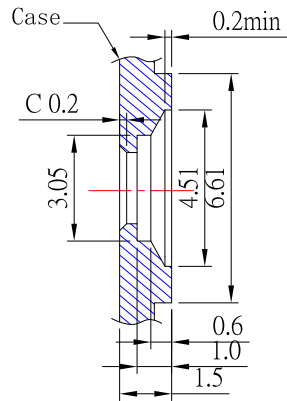
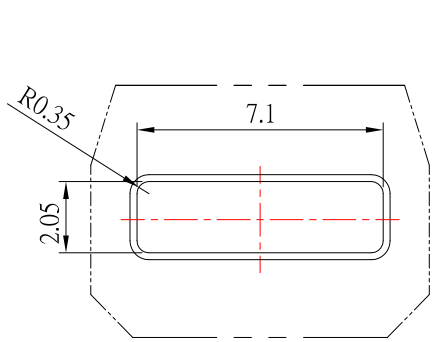


機殼面板對密封圈
與縮量0.40Min

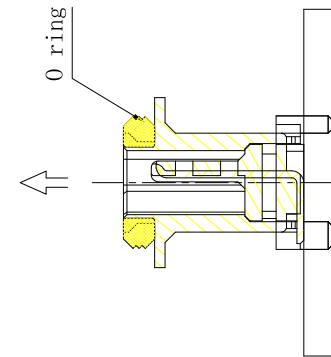
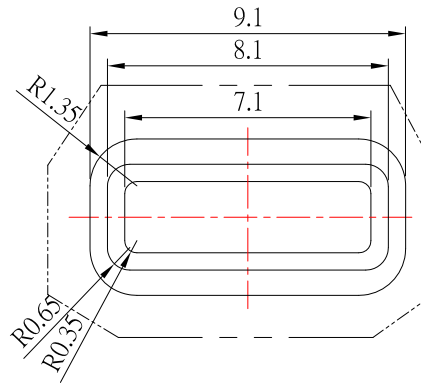


COMPRESSION RATIO TO BE 40%-50%

機殼面板對密封圈與
縮量0.30Min
(建議壓縮量為密封圈
直徑大小40-50%)



RECOMMENDED OPEN DIMENSION OF CASE



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DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	06/30/21		MODLE	MICRO 5B/F 立式SMT IPX7 外殼腳:
CHECKED BY:	DATE	FINISH	DWG NO.	1.15X0.4X0.75mm 支架寬 5.0mm
Jacky Chen	06/30/21		SCALE	1 : 1
APPROVED BY:	DATE	SHEET NO.	PART NO.	MRUSB-5B-WP9VB-x-S382
Tony Kao	06/30/21	1 of 2	MRUSB-5B-WP9VB-x-S382	

2	更新圖面	Jack	063021
1	更新MODLE	Jack	061721
ITEM NO.	DESCRIPTION	DRAWN	DATE